



**MSR
Electronics**



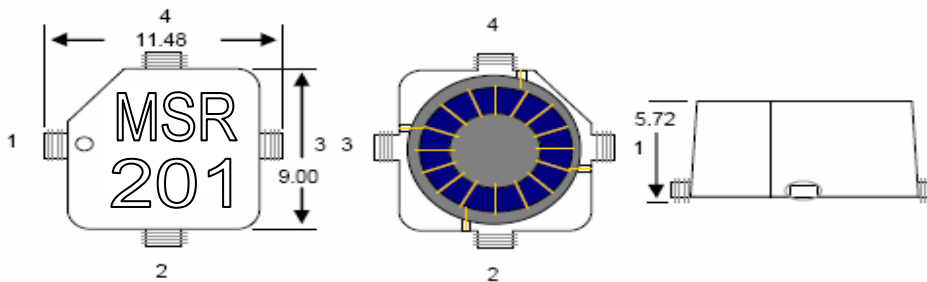
SMD TOROIDAL POWER IND/XFMR

MSP1209 SERIES

RoHS



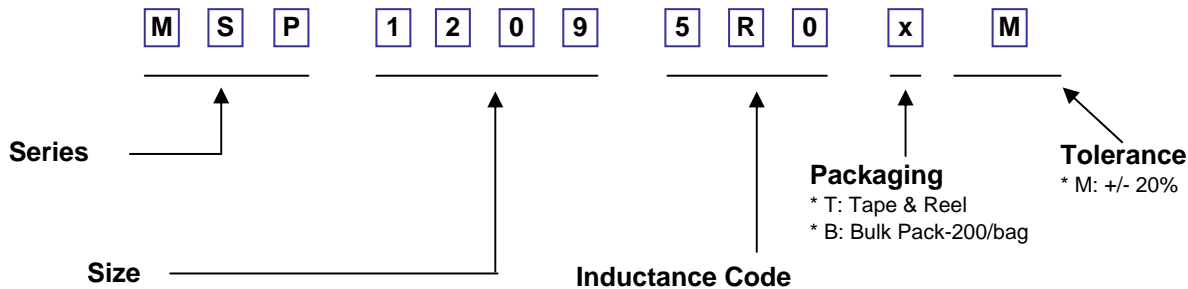
Compliant: Contact
Factory for Copy of
Test Report



FEATURES:

- Solder Heat Resistance: 260 *C @ 30 seconds
- Dimensions (mm)
- Temp Rise = 35 *C @ Irms
- L drops 10% @ Isat
- Operating Temp = -55 to +125 *C
- Spec Ratings are at 25 *C
- Parallel, Series, or Xfmr Mode
- Hipot = 500 Volts

PART NUMBER SYSTEM



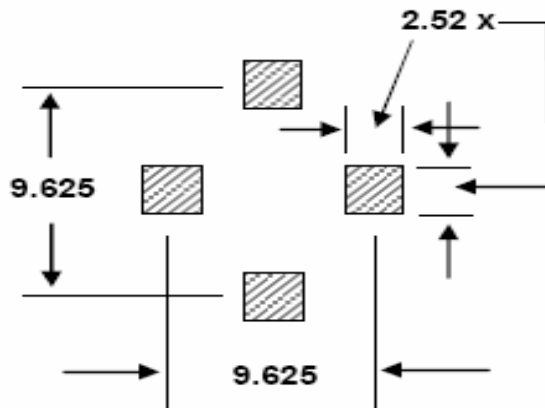
Part Number
MSP1209-5R0xM
MSP1209-8R0xM
MSP1209-100xM
MSP1209-150xM
MSP1209-200xM
MSP1209-250xM
MSP1209-330xm
MSP1209-500xM
MSP1209-680xM
MSP1209-101xM
MSP1209-151xM
MSP1209-201xM
MSP1209-251xM
MSP1209-301xM

PARALLEL			
OCL (uH)	uH @ DC Bias	I (A)	DCR Ohms Max
5.00	3.8	2.41	0.023
8.00	6.1	1.90	0.037
10.0	7.4	1.83	0.040
15.0	11.1	1.45	0.063
20.0	15.2	1.25	0.086
25.0	18.5	1.17	0.098
33.0	24.8	0.98	0.140
50.0	37.5	0.78	0.220
68.0	49.6	0.72	0.260
100	74.0	0.58	0.400
150	111	0.47	0.600
200	150	0.40	0.84
250	193	0.33	1.190
300	225	0.32	1.310

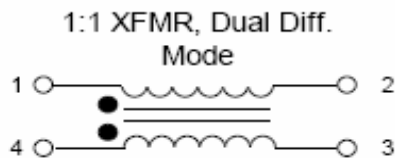
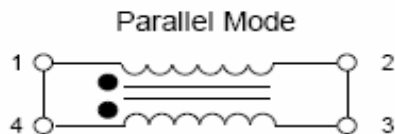
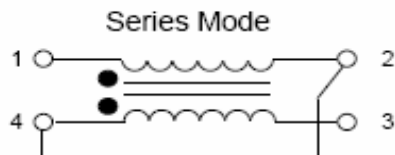
SERIES			
OCL (uH)	uH @ DC Bias	I (A)	DCR Ohms Max
20.0	15.2	1.20	0.092
32.0	23.2	0.95	0.150
40.0	29.6	0.92	0.160
60.0	44.4	0.73	0.250
80.0	60.8	0.63	0.340
100	74.0	0.59	0.390
132	99.2	0.49	0.560
200	150.0	0.38	0.880
272	198.4	0.36	1.040
400	296.0	0.29	1.600
600	444.0	0.24	2.400
800	600.0	0.20	3.360
1000	770.0	0.17	4.760
1200	900.0	0.16	5.240

GENERAL PARAMETERS: Layout, Schematic, Packaging

Solder Pad



SCHEMATICS



PACKAGING

